

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	46	conductiv\$3 near20 unconsolidat\$3	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM-TDB	2003/12/29 15:09	
2	BRS	L2	6	conductiv\$3 near20 unconsolidat\$3 near30 contact\$1	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM-TDB	2003/12/29 15:06	
3	BRS	L3	15	conductiv\$3 near20 unconsolidat\$3 near20 semiconductor	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM-TDB	2003/12/29 15:09	

	U	1	PT	P	Document ID	Issue Date	Pages	Title
1	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20030176018 A1	20030918	12	Assemblies including stacked semiconductor devices separated a distance defined by adhesive material interposed therebetween, packages including the assemblies, and methods
2	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20030176016 A1	20030918	15	Methods for providing support for conductive structures protruding from semiconductor device components
3	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20030098470 A1	20030529	21	Stereolithographically fabricated conductive elements, semiconductor device components and assemblies including such conductive elements, and methods
4	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20030071362 A1	20030417	12	Assemblies including stacked semiconductor devices separated a distance defined by adhesive material interposed therebetween, packages including the assemblies, and methods
5	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20030071340 A1	20030417	13	ASSEMBLIES INCLUDING STACKED SEMICONDUCTOR DEVICES SEPARATED A DISTANCE DEFINED BY ADHESIVE MATERIAL INTERPOSED THEREBETWEEN, PACKAGES INCLUDING THE ASSEMBLIES, AND METHODS
6	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20030045047 A1	20030306	21	Stereolithographically fabricated conductive elements, semiconductor device components and assemblies including such conductive elements, and methods

	U	1	PT	P	Document ID	Issue Date	Pages	Title
7	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20020102829 A1	20020801	21	Stereolithographically fabricated conductive elements, semiconductor device components and assemblies including such conductive elements, and methods
8	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20010051391 A1	20011213	21	Stereolithographically fabricated conductive elements, semiconductor device components and assemblies including such conductive elements, and methods
9	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20010036718 A1	20011101	22	Stereolithographically fabricated conductive elements, semiconductor device components and assemblies including such conductive elements, and methods
10	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6634100 B2	20031021	20	Interposer and methods for fabricating same
11	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6569709 B2	20030527	11	Assemblies including stacked semiconductor devices separated a distance defined by adhesive material interposed therebetween, packages including the assemblies, and methods
12	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6500746 B2	20021231	27	Stereolithographically fabricated conductive elements, semiconductor device components and assemblies including such conductive elements, and methods

	U	1	PT	P	Document ID	Issue Date	Pages	Title
13	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6468891 B2	20021022	19	Stereolithographically fabricated conductive elements, semiconductor device components and assemblies including such conductive elements, and methods
14	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 5895971 A	19990420	13	Semiconductor device with electrical connection between semiconductor chip and substrate less breakable during shrinkage of adhesive compound
15	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 20030045047 A	20030306	21	Conductive element fabrication method for use in semiconductor device, involves forming layers of superimposed mutually adhered unconsolidated conductive material over conductive elements formed by stereolithography